

WLCSP

Package	IO Count		Bump count with die size 7.71X4.91		Die Size	
	Printed Bump	Ball Drop	Min	Max	Printed Bump	Ball Drop
WLCSP	2-107	4-150	192	395	266x566um - 2640x2480um	1000x1000um - 4909µm x 5453µm